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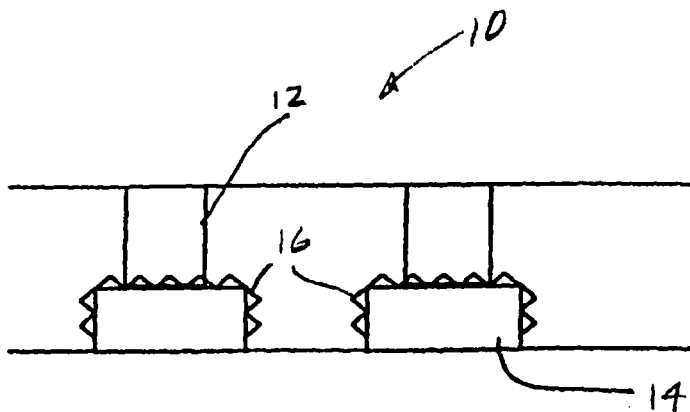


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ACTION

(54) Title: FLIP CHIP INTERCONNECTION STRUCTURE



(57) Abstract: A flip chip structure (10) is formed by mechanically interlocking joining surfaces of a first (12) and a second (14) element. The first element (12), which may be a bump on an integrated circuit chip, includes a soft, deformable material with a low yield strength and high elongation to failure. The surface of the second element (14), which may for example be a substrate pad, is provided with asperities (16) into which the first element (12) deforms plastically under pressure to form the mechanical interlock.

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